

**IN THE CLAIMS**

The following listing of claims is provided in accordance with 37 C.F.R. §1.121:

1. – 10. (canceled).

11. (original) A method for laminating a first substrate to a second substrate, the mutually confronting surfaces of at least one of said first and second substrates being covered at least partially with gold, comprising the following steps:  
mixing a solution comprising sulfur-containing alkoxysilane;  
treating each gold confronting surface with the solution;  
adding sulfur-containing alkoxysilane to an adhesive material;  
applying the adhesive material on at least one of the confronting surfaces of said first and second substrates; and  
holding said first and second substrates in a fixed relationship while the adhesive material therebetween sets.

12. (original) The method as recited in claim 11, wherein the concentration of sulfur-containing alkoxysilane in the solution is in the range of 0.1 to 10%.

13. (original) The method as recited in claim 11, wherein the concentration of sulfur-containing alkoxysilane in the adhesive material is in the range of 0.1 to 10%.

14. (original) The method as recited in claim 11, wherein the sulfur-containing alkoxysilane is mercaptopropyl trimethoxysilane.

15. (original) The method as recited in claim 11, wherein the sulfur-containing alkoxysilane is disulfidepropyl triethoxysilane.

16. (original) The method as recited in claim 11, wherein the adhesive material is bispheno-A epoxy resin cured using an aliphatic amine.

17. – 20. (canceled).

21. (original) A laminated structure comprising first and second substrates having mutually confronting surfaces, the mutually confronting surfaces of at least one of said first and second substrates being covered at least partially with gold, and the mutually confronting surfaces being bonded by a thin layer of adhesive material, wherein the adhesive material has an adhesion-promoting agent blended therein, said adhesion-promoting agent being a sulfur-containing alkoxysilane.

22. (original) The laminated structure as recited in claim 21, wherein the concentration of sulfur-containing alkoxysilane in the adhesive material is about 1%.

23. (original) The laminated structure as recited in claim 21, wherein the sulfur-containing alkoxysilane is mercaptopropyl trimethoxysilane.

24. (original) The laminated structure as recited in claim 21, wherein the sulfur-containing alkoxysilane is disulfidepropyl triethoxysilane.

25. (original) The laminated structure as recited in claim 21, wherein the adhesive material is bisphenol-A epoxy resin cured using an aliphatic amine.

26. (original) The laminated structure as recited in claim 21, wherein both of the mutually confronting surfaces are at least partially covered with gold.

27. (original) The laminated structure as recited in claim 21, wherein said first substrate is made of piezoelectric ceramic material and said second substrate is made of dielectric material.

28. – 31. (canceled).